## INTEGRATED EM & THERMAL SIMULATIONS WITH UPGRADED VORPAL SOFTWARE

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#### Summary of Talk

- Progress in Thermal Simulation Capability
- Benchmarking
  - EM
  - Thermal
- Cut-cell Finite-Difference Thermal Algorithm
- Ongoing Tasks

## The evolution of multi-physics capability in Vorpal

• Vorpal is a Finite-Difference Time-Domain Electromagnetic Particle-In-Cell simulation tool, with a history of application to laser wakefield plasma accelerators, and srf cavity modeling.



- But Vorpal also has general PDE solver capability ... so ... *in principle* ... replace curl-operations with divergencegradient, to go from Maxwell to heat conduction problem.
- This project has taken the idea from principle to realization.
  - Cut-cell geometry in both EM and thermal.
  - Cryogenic non-linear thermal properties.



## Vorpal thermal modeling capability is now well beyond proof-of-principle

- From very simplistic 2D geometry, confined to the grid planes
  ⇒ Cut-cell 3D geometry based on CAD input.
- From single material ⇒ arbitrary composition, allowing several order magnitude difference in thermal conductivity, k.



Capability is being tested on a specific benchmark problem

Benchmark is the <u>HOM coaxial coupler</u> <u>feed-through</u>, for which prior, and ongoing, analysis exists, and for which laboratory measurement data exists.

(G. Wu, H. Wang, R. Rimmer, and C. Reece, "Electromagnetic simulations of Coaxial Type HOM Couplers," JLAB-ACC-05-418, also THP58 in Proceedings of 12<sup>th</sup> SRF Workshop, Cornell University, July 2005.)





#### Electromagnetic code benchmark is consistent

(See Poster TUP107, G. Cheng et al., this conference.)

- The outer coaxial probe tip of the coupler is extended to form a coaxial line.
- 1 watt power is fed into probe end.
- Electric and magnetic profiles, S11, and S21, from MWS, ANSYS, HFSS, and Vorpal are compared.
- Excellent E field, B field more sensitive to grid resolution.





Distance along HOM coupler axis from pick-up port (mm)

## TECH

# Variety of materials makes the thermal problem challenging

- There are a dozen parts to this assembly, made from ten different materials, with nearly  $10^5$  variation in thermal conductivity, k(T).
- Fully non-linear temperature dependent k(T) is implemented.
- Present static-solver is an accelerated Richardson iteration, but copperstainless interface slows convergence. A more capable implicit solve will be used in the future, both for convergence, and for time-dependence.





## Thermal code & measurement benchmark is in progress

- Fixed heat flux, 50 milliwatts, from warm coax line into feedthrough, with cryogenic coolling, 2K, on strap.
- Compare ANSYS, Vorpal, and measurement. Adapter's center coax is hottest, at ~100 K. Sensitive to bushing





## Our finite-difference based thermal analysis is somewhat novel

- We are doing finite-difference based thermal analysis, rather than finite-element. For accurate geometry, we've extended the "cut-cell" idea, which we use for EM, over to thermal.
- Yee-cell finite-volumes treatment,  $c \int \partial_t T d^3 V = -\oint \mathbf{Q} \cdot d\mathbf{A}$ with temperature at center of cell, heat-flux at faces of cell. Thermal conductivity, k(T), evaluated for each face.
- A choice to make for heat flux:  $\mathbf{Q} = -k(T)\nabla T$ accurate parallel,  $kdA = \int kdA$ accurate serial,  $k^{-1}dl = \int k^{-1}dl$
- Have chosen accurate parailel, since this treats strong material discontinuity.
- Improvements to this are being considered, for better serial transport.



#### Implementations are designed for reusability

- Heavy use of "macros" pre-processing capabilities hides much of the usual input file detail that is not physics related.
- Macros are "part-based", for example:

# import and specify physical geometry newCADpart(part02InnerNadapter, Inconel X750, HOMFeedThru(02).stl) AlMq, HOMFeedThru(03).stl) newCADpart(part03gasket, newCADpart(part04smallDiaSaphire, Saphire, HOMFeedThru(04).stl) newCADpart(part06OuterNadapter, HOMFeedThru(06).stl) SS 304, newCADpart(part07portTube, Nb RG, HOMFeedThru(07).stl) Nb55Ti, newCADpart(part08interiorFlange, HOMFeedThru(08).stl) newCADpart(part09sleeve, Cu OFE 200, HOMFeedThru(09).stl) newCADpart(part10exteriorFlange, SS 316L, HOMFeedThru(10).stl) newCADpart(part11bigDiaSaphire, Saphire, HOMFeedThru(11).stl) newCADpart(part12probeTip, Nb RRR, HOMFeedThru(12).stl) newExpressionPart(bracket, Cu OFE 200, pipe(y-YBGN BRACKET,z,x,... newExpressionPart(strap, Cu OFE\_strap, box(x-XBGN\_STRAP,y-YBGN\_STRAP,z,...

addHeatSource(adapterHeatSource00,IX0\_ADAPTER\_SOURCE,IY\_ADAPTER\_SOURCE,...

addHeatStation(probeStationMM,IXM\_PROBE\_SOURCE,IY\_PROBE\_STATION,...

• A more "user friendly" wrapping of macros is topic of inquiry.



## **Ongoing Work for Phase II, Year 2**

• Additional benchmarking and design analysis.

#### New thermal solver

- First as a fixed coefficient matrix inversion.
- Then as a non-linear iteration on coefficients.
- Ultimate purpose is legitimate time-dependent modeling, particularly of a quench event.
- Better computational efficiency
  - Some fields over surface domain, rather than entire volume.
  - Consolidation of material operations, cut-cell k(T) especially.
- Application of non-uniform grid.
- Additional multi-physics
  - Non-linear magnetic material, for example.



#### Summary

- We have realized much of the hoped-for capability from the original proof-of-principle thermal analysis.
- We've produced a fairly novel finite-difference cut-cell thermal simulation capability that interacts easily with the pre-existing cut-cell electromagnetic modeling capability.
- We've benchmarked the new capability on a coaxial HOM coupler feed-through.
- We're ongoing with the 2<sup>nd</sup> year of the Phase II SBIR.